

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIN-LIANG CHEN</td> <td>11/22/2013</td> </tr> <tr> <td>WEI-TING LIN</td> <td>11/22/2013</td> </tr> <tr> <td>KUAN-LIN HO</td> <td>11/22/2013</td> </tr> <tr> <td>YU-CHIH LIU</td> <td>11/22/2013</td> </tr> <tr> <td>CHUN-CHENG LIN</td> <td>11/22/2013</td> </tr> <tr> <td>SHIH-YEN LIN</td> <td>11/22/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIN-LIANG CHEN	11/22/2013	WEI-TING LIN	11/22/2013	KUAN-LIN HO	11/22/2013	YU-CHIH LIU	11/22/2013	CHUN-CHENG LIN	11/22/2013	SHIH-YEN LIN	11/22/2013
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CHUN-CHENG LIN	11/22/2013														
SHIH-YEN LIN	11/22/2013														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.														
Street Address:	NO. 8, LI-HSIN RD. 6														
Internal Address:	HSIN-CHU SCIENCE PARK														
City:	HSIN-CHU														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14093856</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14093856										
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Application Number:	14093856														
CORRESPONDENCE DATA															
Fax Number:	(216)502-0601														
Phone:	216-502-0600														
Email:	docketing@eschweilerlaw.com														
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>															
Correspondent Name:	ESCHWEILER & ASSOCIATES, LLC.														
Address Line 1:	629 EUCLID AVENUE, SUITE 1000														
Address Line 2:	NATIONAL CITY BANK BUILDING														
Address Line 4:	CLEVELAND, OHIO 44114														
ATTORNEY DOCKET NUMBER:	TSMCP374US														
<b>PATENT</b>															

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NAME OF SUBMITTER:	THOMAS G. ESCHWEILER
Signature:	/Thomas G. Eschweiler/
Date:	12/02/2013
<p>Total Attachments: 8 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif source=Assignment#page6.tif source=Assignment#page7.tif source=Assignment#page8.tif</p>	

TSMC Docket No. TSMC2013-0181

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Filing Date

**PATENT ASSIGNMENT**

**PARTIES TO THE ASSIGNMENT**

Assignor(s):

Chin-Liang Chen  
No. 379, Songjiang St.  
Sanmin Dist.  
Kaohsiung City 807  
Taiwan (R.O.C.)

Assignor(s):

Wei-Ting Lin  
2F, No. 4, Aly. 2, Ln. 668, Minzu E. Rd.  
Songshan Dist.  
Taipei City 105  
Taiwan (R.O.C.)

Assignor(s):

Kuan-Lin Ho  
P.O. Box 2-130 Hsinchu  
Hsinchu City 30099  
Taiwan (R.O.C.)

Assignor(s):

Yu-Chih Liu  
2F, No. 8, Ln. 71, Sec. 2, Anhe Rd.  
Daan Dist.  
Taipei City 106  
Taiwan (R.O.C.)

Assignor(s):

Chun-Cheng Lin  
3F, No. 153, Yumin Rd.  
Tucheng Dist.  
New Taipei City 236  
Taiwan (R.O.C.)

Assignor(s):

Shih-Yen Lin  
4F, No. 414, Bihua St.  
Sanchong Dist.  
New Taipei City 241  
Taiwan (R.O.C.)

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Assignee:

Taiwan Semiconductor Manufacturing Co., Ltd.  
No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park  
Hsin-Chu, Taiwan 300-77  
Republic of China

**AGREEMENT**

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled  
**"ADHESIVE PATTERN FOR ADVANCE PACKAGE RELIABILITY  
IMPROVEMENT"** for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this  
Assignment on the same day as he/she signs the Declaration and Power of  
Attorney); or

was filed on \_\_\_\_\_ and accorded U.S. Serial No. \_\_\_\_\_; or

I hereby authorize and request my attorney associated with Customer No.  
107476, to insert on the designated lines below the filing date and application  
number of said application when known:

U.S. Serial No. \_\_\_\_\_

filed on \_\_\_\_\_

WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is  
desirous of acquiring the entire right, title and interest in and to the invention and in and to  
any letters patent that may be granted therefore in the United States and in any and all  
foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of  
which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto  
ASSIGNEE its successors and assigns, the entire right, title and interest in and to said

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invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

2013-11-22  
Date

Chin-Liang Chen  
Name 1<sup>st</sup> Inventor Chin-Liang Chen

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2013.11.22  
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Wei Ting Lin  
Name 2<sup>nd</sup> Inventor Wei Ting Lin

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Date

KUAN-LIN HO

Name 3<sup>rd</sup> Inventor Kuan-Lin Ho

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Filing Date

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Date

Liu Yu-Chih  
Name 4<sup>th</sup> Inventor Yu-Chih Liu



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Date

Chun-Cheng Lin

Name 5<sup>th</sup> Inventor Chun-Cheng Lin

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Filing Date

11/22/2013  
Date

Shih-Yen Lin  
Name 6<sup>th</sup> Inventor Shih-Yen Lin